Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range 55 °C to 110 °C
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

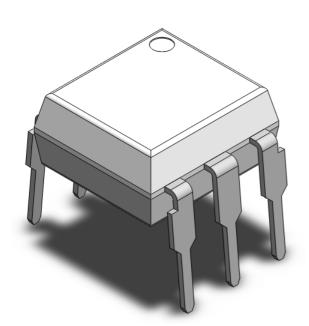
Applications

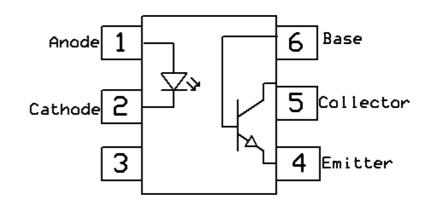
- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Description

The 4N25, 4N26, 4N27, 4N28, 4N35, 4N36, 4N37, 4N38, H11A1, H11A2, H11A3, H11A4, H11A5 series consists of a photo transistor optically coupled to a gallium arsenide Infrared-emitting diode in a 6-lead DIP package different lead forming options.

Package Outline





Schematic

Note: Different bending options available. See package dimension.

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Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5000	VRMS	
TOPR	Operating temperature	-55 ~ +110	°C	
Тѕтс	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature	260	°C	
Emitter				
lF	Forward current	60	mA	
IF(TRANS)	Peak transient current (≤1µs P.W,300pps)	1	A	
VR	Reverse voltage	6	V	
PD	Power dissipation	100	mW	
Detector				
PD	Power dissipation	150	mW	
BVCEO	Collector-Emitter Breakdown Voltage	80	V	
Вусво	Collector-Base Breakdown Voltage	80	V	
BVECO	Emitter-Collector Breakdown Voltage	7	V	
B _{VEBO}	Emitter-Base Breakdown Voltage	7	V	



Electrical Characteristics $T_A = 25 \ \ C$ (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I⊧=10mA		1.24	1.4	V	
I _R	Reverse Current	$V_R = 6V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	45	-	pF	

Detector Characteristics

Symbol	Pa	rameters	Test Conditions	Min	Тур	Max	Units	Notes
BVCEO	Collector-Emitter	Breakdown	Ic= 0.1mA	80	-	-	V	
BVECO	Emitter-Collector	Breakdown	I _E = 0.1mA	7	-	-	V	
Вусво	Collector-Base Breakdown		Ic= 0.1mA	80	-	-	V	
B _{VEBO}	Emitter-Base Breakdown		I _E = 0.1mA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	4N25,4N26,4N27,4N28 H11A1,A2,A3,A4,A5	V _{CE} = 10V, I _F =0mA	-	-	50	nA	
		4N35,4N36,4N37,4N38	V_{CE} =60V, I _F =0mA	-	-	50	nA	
Ісво	Collector-Base Dark Current		V _{CB} = 10V, I _F =0mA	-	-	20	nA	

Transfer Characteristics

Symbol	F	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
		4N35, 4N36, 4N37		100	-	-	-	
	Current	4N25,4N26, 4N38,		20				
CTR	Current	H11A2, H11A3		20	-	-	%	
	Transfer	4N27, 4N28, H11A4	I _F = 10mA, V _{CE} = 10V	10	-	-	70	
	Ratio	H11A1		50	-	-		
		H11A5		30	-	-		
		4N25,4N26,	I _F = 50mA, I _C = 2mA	-	-	0.5		
	Collector-E	4N27,4N28						
	mitter	4N35,4N36,4N37		-	-	0.3	N	
V _{CE(SAT)}	Saturation	H11A1,H11A2,	I⊧= 10mA, Ic= 0.5mA			0.4	V	
	Voltage	H11A3,H11A4,H11A5		-	-	0.4		
		4N38	I⊧= 20mA, Ic= 4mA	-	-	1.0		
Rio	Isolation Resistance		V _{IO} = 500V _{DC}	1x10 ¹¹			Ω	
Сю	Isolation Capacitance		f= 1MHz		0.25		pF	

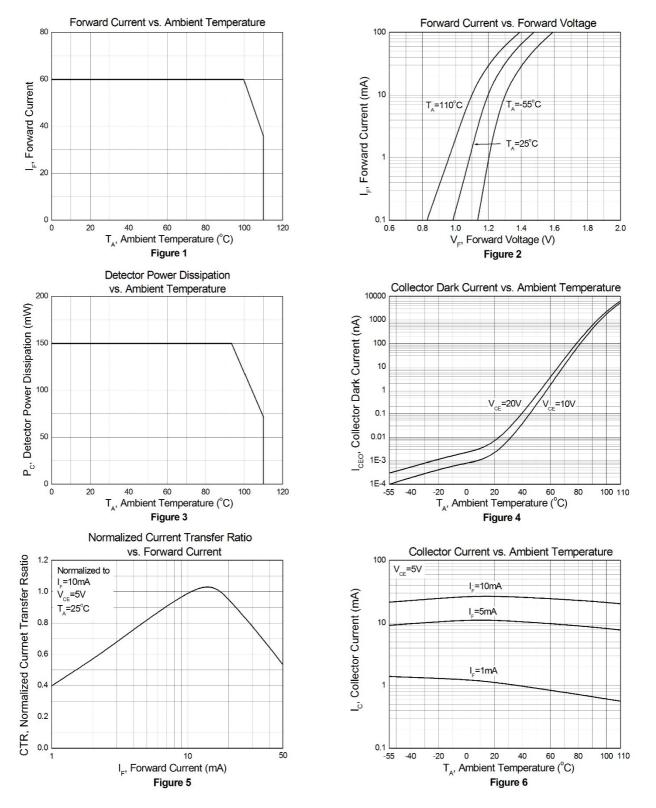


Switching Characteristics

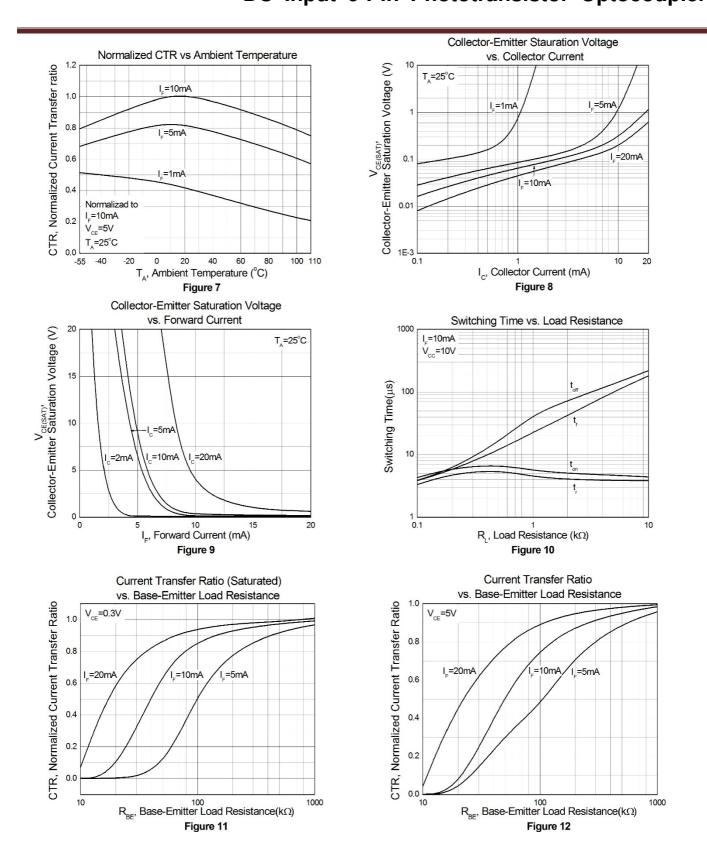
Symbol	F	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
		4N25,4N26,4N27,4N28	I_{F} = 10mA, V_{CC} = 10V, R_{L} =		4.3	0.0		
+	Turn On	H11A1,A2,A3,A4,A5	100Ω	-	4.3	9.8		
t _{on}	Time	4N35,4N36,4N37,4N38	$I_c= 2mA$, $V_{CC}= 10V$, $R_L=$	-	9.8	11.5	μs	
		41135,41130,41137,41130	100Ω					
		4N25,4N26,4N27,4N28	$I_{F}=10mA,V_{CC}=10V,R_{L}=$	-	3.9	9.8		
t	Turn Off	H11A1,A2,A3,A4,A5	100Ω		3.9			
t _{off}	Time	4N35,4N36,4N37,4N38	$I_c= 2mA$, $V_{CC}= 10V$, $R_L=$	-	- 6.9 11.5		μs	
		41133,41130,41137,41130	100Ω			11.5		



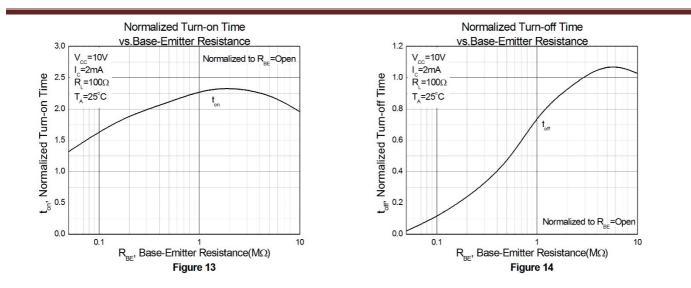
Typical Characteristic Curves







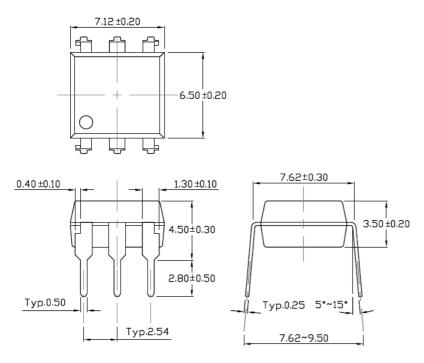




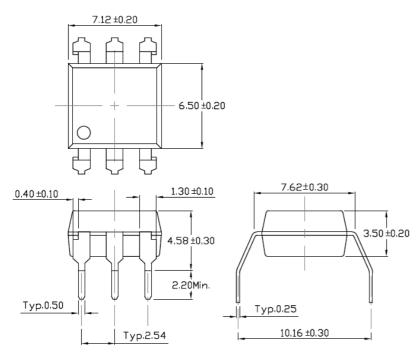


Package Dimension Dimensions in mm unless otherwise stated

Standard DIP – Through Hole

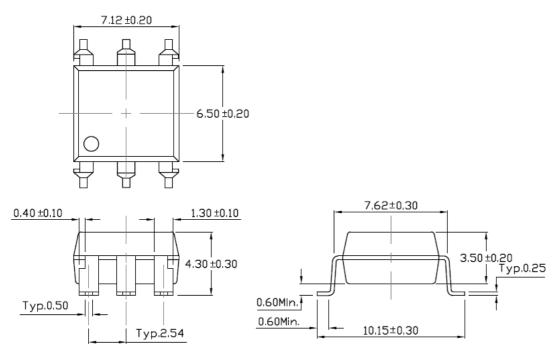


Wide Lead Forming – Through Hole (M Type)

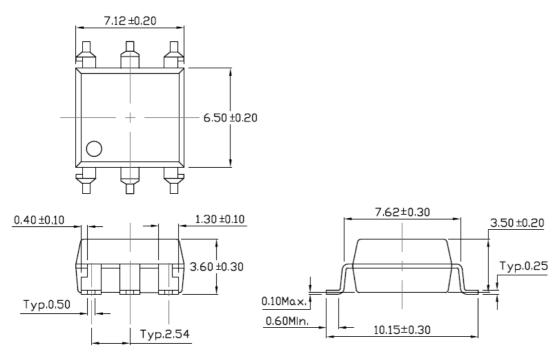




Surface Mount Forming (S Type)

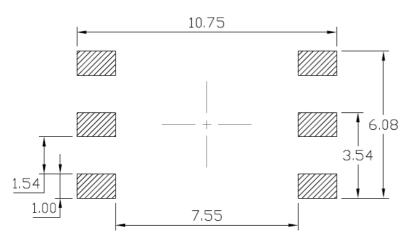


Surface Mount Forming (Low Profile) (SL Type)

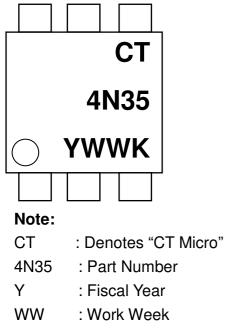




Recommended Solder Mask Dimensions in mm unless otherwise stated



Marking Information



K : Manufacturing Code



Ordering Information

4N2X(Y)(Z)-G, 4N3X(Y)(Z)-G

X = Part No. (X=5,6,7 or 8)

Y = Lead form option (S, SL, M or none)

Z = Tape and reel option (T1, T2 or none)

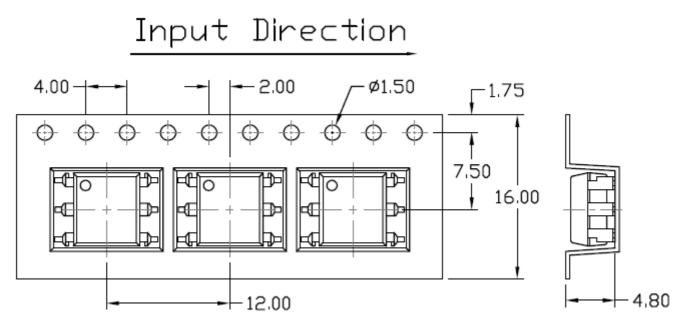
G= Material option (G: Green, None: Non-green)

Option	Description	Quantity
None	Standard 6 Pin Dip	65Units/Tube
М	Wide Lead Forming	65Units/Tube
S(T1)	Surface Mount Lead Forming – With Option A Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option B Taping	1000 Units/Reel
SL(T1)	Surface Mount Lead Forming(Low Profile) – With Option A Taping	1000 Units/Reel
SL(T2)	Surface Mount Lead Forming(Low Profile) – With Option B Taping	1000 Units/Reel

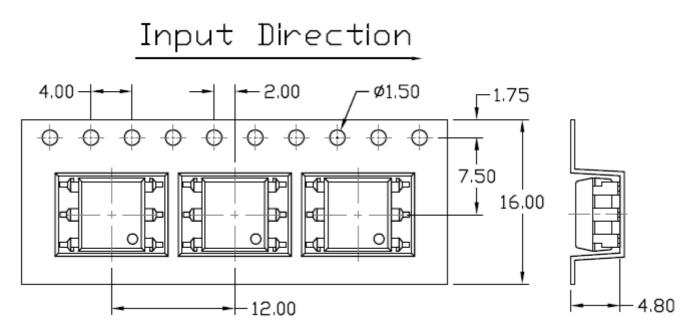


Carrier Tape Specifications Dimensions in mm unless otherwise stated

Option S(T1) & SL(T1)

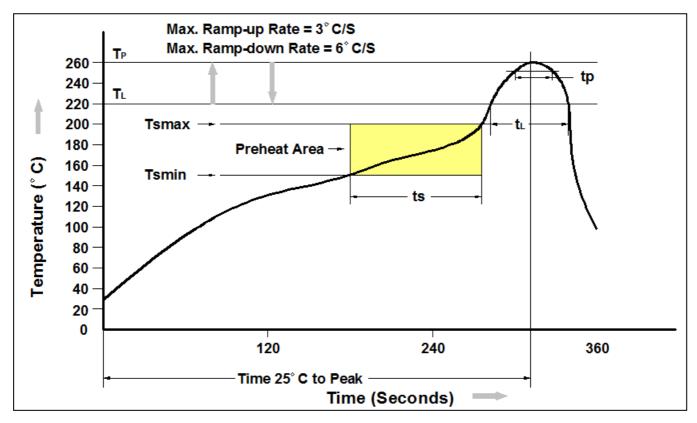


Option S(T2) & SL(T2)





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150 <i>°</i> C
Temperature Max. (Tsmax)	200 <i>°</i> C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (TL)	217 <i>°</i> C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260 ℃ +0 ℃ / -5 ℃
Time (t _P) within 5℃ of 260℃	30 seconds
Ramp-down Rate (TP to TL)	6℃/second max
Time 25 ℃ to Peak Temperature	8 minutes max.



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